External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00336	1.06	0.03586
		Silicon (Si)	7440-21-3	0.31362	98.94	3.3473
			Subtotal	0.31698	100	3.38316
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03757	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01127	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03757	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.48517	99.77	400.0777
			Subtotal	37.57158	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84682	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.93088	10.0	63.3
	Filler	Silica fused	60676-86-0	50.41244	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11862	0.2	1.266
			Subtotal	59.30876	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34237	100.0	25
			Subtotal	2.34237	100	25
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00456	2.0	0.04866
	Lead alloy	Silver (Ag)	7440-22-4	0.0057	2.5	0.06082
	Lead alloy	Lead (Pb)	7439-92-1	0.21769	95.5	2.32335
			Subtotal	0.22795	100	2.43283
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.23236	100.0	2.48
			Subtotal	0.23236	100	2.48
			Total	100	100	1067.29599

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